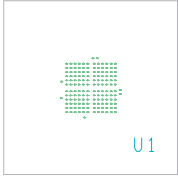


BGA Pad = 0.254mm
BGA Pad Soldermask = 0.4064mm
BGA Via = 0.127mm Pad,
0.127mm Drill
BGA Tracks = 0.1016mm Width,
0.1016mm Spacing.
NUMBER OF LAYERS = 8

FABRICATION DRAWING



DRILL CHART: TOP to L2_SIG1			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	6.0	PLATED	38

DRILL CHART: TOP to L4_SIG2			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	6.0	PLATED	32

DRILL CHART: TOP to L5_SIG3			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	6.0	PLATED	31

DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILS			
FIGURE	SIZE	PLATED	QTY
.	6.0	PLATED	50